Polyamide/polyolefin-based laminate

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EP1031411
US5869190
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Good adhesion between layers is achieved in a multilayer composite having the following layers: I. a layer I of a polyamide molding composition; II. a layer II of a bonding agent having at least 50% by weight of a mixture of a) from 30 to 70 parts by volume of a polymer selected from a polyamide and a polyamine-polyamide copolymer, b) from 0.1 to 70 parts by volume of an olefin polymer containing a functional group, c) from 69.9 to 0 parts by volume of an unfunctionalized polyolefin, where the sum of the parts by volume of a), b) and c) is 100; and III. a layer III of a polyolefin molding composition.

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